

# PREFACE

Dear Distinguished Delegates and Guests,

2<sup>nd</sup> International Conference on Intelligent Structure and Vibration Control 2012 (ISVC2012) was held in Chongqing, China, from March 16-18, 2012, serving as a platform for expertise exchange. ISVC 2012 had drawn the attention of researchers from various disciplines: Advanced Intelligent Structure, Bio-inspired Smart Materials and Structures, Materials for energy storage, Active Materials, Mechanics and Behavior, Vibration and Control, Modeling, Simulation, Control and Applications, Fuzzy System and Fuzzy Control, Management Information Systems, etc.

Persons who attended the conference were engineers, scientists, managers of various companies and professors of the universities abroad and home. We have had record number of submission 452 this year. Only original and unpublished paper would be considered, and 80 papers have been accepted for presentation at the conference and will be published by TTP, in Applied Mechanics and Materials (AMM) Journal (ISSN: 1660-9336), which is online available in full text via the platform [www.scientific.net](http://www.scientific.net). AMM should be indexed by EI according the previous TTP index results.

We express our special gratitude to all the members of the General Committee Chairs, Program Committee Chairs, Technical Program Committee and Steering Committee who worked so hard to prepare the conference and who supported the conference so professionally.

Our deep thanks also go to the sponsors: Shanghai Jiao Tong University, Nanyang Normal University, Hebei Polytechnic University, Henan Institute of Science and Technology, Chongqing University of Arts and Sciences, Hunan Institute of Engineering, their kind support in making ISVC 2012 possible.

Finally, we would like to thanks all the authors, speakers and participants of this conference for taking part in and contributing to the International Conference on Intelligent Structure and Vibration Control 2012.

We hope you have a unique, rewarding and enjoyable week at ISVC 2012 in Chongqing.

With our warmest regards,

ISVC2012 Organizing Committees

March 16-18, 2012

Chongqing, China

# ISVC 2012

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